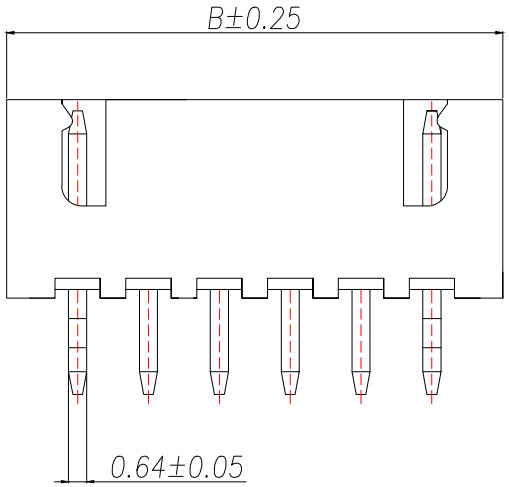
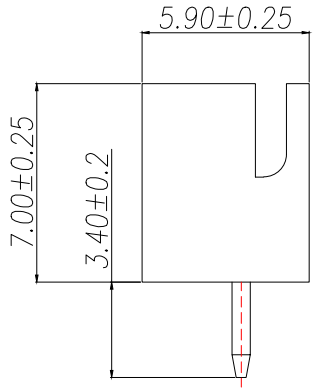
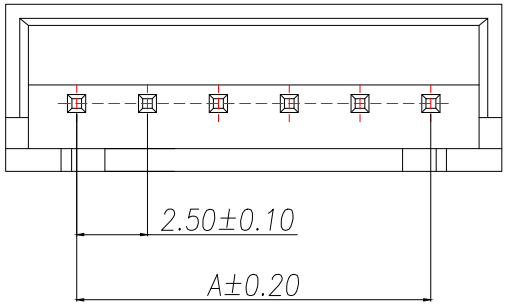
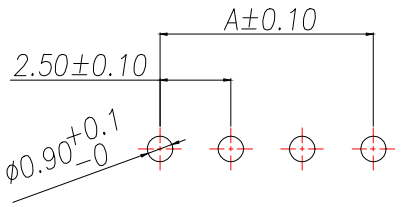



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

| Part No | Pin | A | B |
|---|---|---|---|
| XH2.5 -2PZZ | 2 | 2.50 | 7.50 |
| XH2.5 -3PZZ | 3 | 5.00 | 10.00 |
| XH2.5 -4PZZ | 4 | 7.50 | 12.50 |
| XH2.5 -5PZZ | 5 | 10.00 | 15.00 |
| XH2.5 -6PZZ | 6 | 12.50 | 17.50 |
| XH2.5 -7PZZ | 7 | 15.00 | 20.00 |
| XH2.5 -8PZZ | 8 | 17.50 | 22.50 |
| XH2.5 -9PZZ | 9 | 20.00 | 25.00 |
| XH2.5 -10PZZ | 10 | 22.50 | 27.50 |
| XH2.5 -11PZZ | 11 | 25.00 | 30.00 |
| XH2.5 -12PZZ | 12 | 27.50 | 32.50 |
| XH2.5 -13PZZ | 13 | 30.00 | 35.00 |
| XH2.5 -14PZZ | 14 | 32.50 | 37.50 |
| XH2.5 -15PZZ | 15 | 35.00 | 40.00 |
| XH2.5 -16PZZ | 16 | 37.50 | 42.50 |
| XH2.5 -17PZZ | 17 | 40.00 | 45.00 |
| XH2.5 -18PZZ | 18 | 42.50 | 47.50 |
| XH2.5 -19PZZ | 19 | 45.00 | 50.00 |
| XH2.5 -20PZZ | 20 | 47.50 | 52.50 |

技术要求:

1.塑件材料:PA66(UL-94V-0)

2.接触件:黄铜镀锡

3.接触电阻:≤10mΩ

4.绝缘电阻:≥100MΩ

5.额定电压:250V AC DC

6.额定电流:2.0A AC DC

7.耐压:能承受1000V AC/Minute

8.工作温度:-25°~+85°

9.可焊性试验:浸锡面积≥95%温度235°$^{+5}_{-0}$,时间2.5±0.5秒

10.铅和镉等六大有害物质含量要符合环保要求.

| 序号 | 名称 | 材料 | 数量 | 备注 |
|---|---|---|---|---|
| 2 | 端子Contact | 黄铜 | N*1 | 电镀(锡):整个表面镀底镍30u"MIN,再镀锡80u"MIN |
| 1 | 基座Wafer | PA66(UL94V-0) | 1 | 白色 |

| 制图 DRAWN | 变更内容 DESCRIPTION | 日期 DATE |
|---|---|---|
| | | |
| | | |
| | | |

| GENERL TOLERANCE | |
|---|---|
| .X±0.20 | ±2° |
| .XX±0.10 | |
| .XXX±0.05 | |

| | | | |
|---|---|---|---|
| 制图 DRAWING | ROSE | | |
| 审核 CHECK | LEO | | |
| 核准 APPROVAL | JOHN | | |
| 单位 UNITS | MM | 比例 SCALE | 1:1 |

| | | | |
|---|---|---|---|
| 料号 PART NO. | BTC-XH2.5-N*A | 版本 REV. | A |
| 品名 TITLE | WAFER XH2.54MM 直针 | 页次 SHEET | 1/1 |
| 客户料号 CUTM.NO. | | | |

深圳市宝通成电子有限公司